

## SN74AHCT1G04 シングル・インバータ・ゲート

### 1 特長

- 動作範囲: 4.5V~5.5V
- 最大  $t_{pd}$ : 7ns (5V 時)
- 低消費電力、最大  $I_{CC}$  10 $\mu$ A
- 5V で  $\pm 8$ mA の出力駆動能力
- 入力は TTL 電圧互換
- JESD 17 準拠で 250mA 超のラッチアップ性能

### 2 アプリケーション

- ノート PC
- 電子 POS
- メディカル・モニタ
- モータ制御: AC 誘導
- ネットワーク・スイッチ
- テスト

### 3 概要

SN74AHCT1G04 には 1 つのゲートが搭載されています。このデバイスは、ブール関数  $Y = \bar{A}$  を実行します。

#### パッケージ情報

部品番号	パッケージ (1)	パッケージサイズ (2)	本体サイズ (3)
SN74AHCT1G04	DBV (SOT-23, 5)	2.8mm × 2.8mm	2.9mm × 1.6mm
	DCK (SC-70, 5)	2.00mm × 1.25mm	2.00mm × 1.25mm

- 詳細については、[セクション 11](#) を参照してください。
- パッケージサイズ (長さ×幅) は公称値で、該当する場合はピンも含まれます。
- 本体サイズ (長さ×幅) は公称値であり、ピンは含まれません。

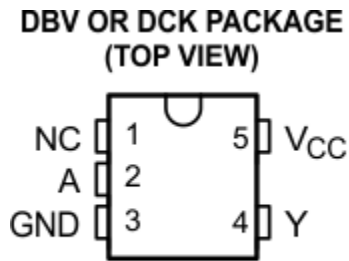


概略回路図

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## 4 Pin Configuration and Functions



NC – No internal connection

**表 4-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NO.	NAME		
1	NC	—	No Connection
2	A	I	Input A
3	GND	—	Ground Pin
4	Y	O	Output Y
5	V <sub>CC</sub>	—	Power Pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	–0.5	7	V
V <sub>I</sub> <sup>(2)</sup>	Input voltage range	–0.5	7	V
V <sub>O</sub> <sup>(2)</sup>	Output voltage range	–0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	–20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub>	±20	mA
I <sub>O</sub>	Continuous output current	V <sub>O</sub> = 0 to V <sub>CC</sub>	±25	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [セクション 5.3](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±1500
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN <sup>(1)</sup>	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		V
V <sub>IL</sub>	Low-level Input voltage		0.8	V
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current		–8	mA
I <sub>OL</sub>	Low-level output current		8	mA
Δt/Δv	Input Transition rise or fall rate		20	ns/V
T <sub>A</sub>	Operating free-air temperature	–40	125	°C

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* ([SCBA004](#))

## 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN74AHCT1G04		UNIT
		DBV	DCK	
		5 PINS		
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	278	289.2	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	180.5	205.8	
R <sub>θJB</sub>	Junction-to-board thermal resistance	184.4	176.2	
ψ <sub>JT</sub>	Junction-to-top characterization parameter	115.4	117.6	
ψ <sub>JB</sub>	Junction-to-board characterization parameter	183.4	175.1	
R <sub>θJC(bot)</sub>	Junction-to-case (bot) thermal resistance	N/A	N/A	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

## 5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		–40°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	High level output voltage I <sub>OH</sub> = –50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
			3.94			3.8		3.8		
V <sub>OL</sub>	Low level output voltage I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1		0.1	V
					0.36		0.44		0.44	
I <sub>I</sub>	Input leakage current V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1		±1	μA
I <sub>CC</sub>	Supply current V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			1		10		10	μA
ΔI <sub>CC</sub> <sup>(1)</sup>	Supply-Current Change One input at 3.4 V, Other Inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5		1.5	mA
C <sub>i</sub>	Input Capacitance V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4			10		10	pF

(1) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## 5.6 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see [Load Circuit And Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	OUTPUT CAPACITANCE	T <sub>A</sub> = 25°C		–40°C to 85°C		–40°C to 125°C		UNIT
				TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 15 pF	4.7		1	7.5	1	8	ns
t <sub>PHL</sub>				4.7		1	7.5	1	8	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 50 pF	5.5		1	8.5	1	9	ns
t <sub>PHL</sub>				5.5		1	8.5	1	9	

### 5.7 Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load, $f = 1\text{ MHz}$	14	pF

### 5.8 Typical Characteristics

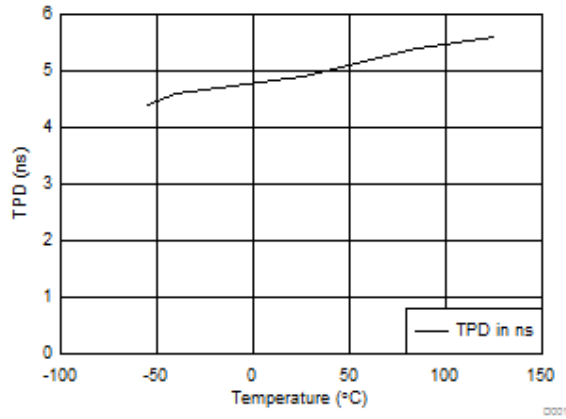
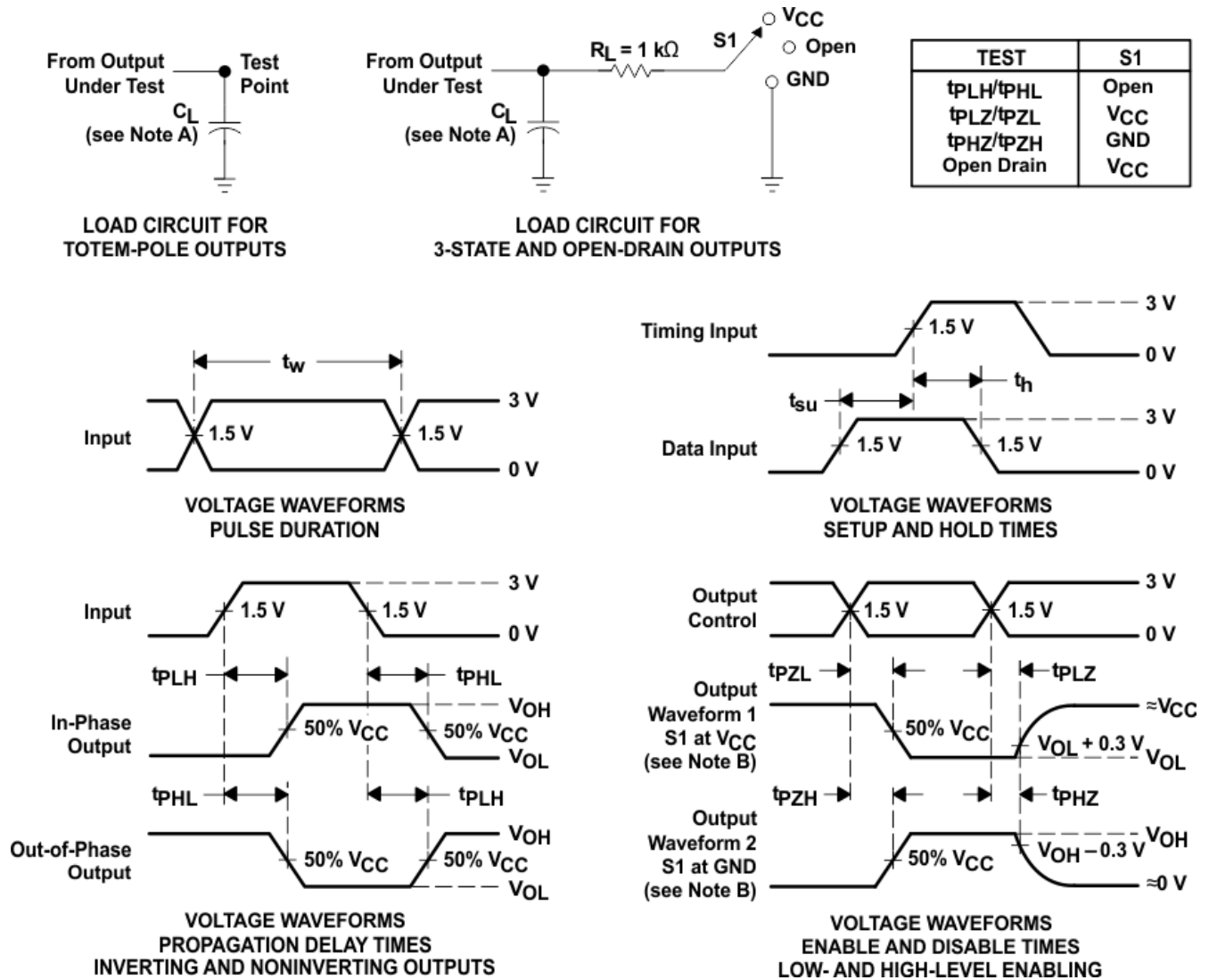


図 5-1. TPD vs Temperature

## 6 Parameter Measurement Information



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

图 6-1. Load Circuit And Voltage Waveforms

## 7 Detailed Description

### 7.1 Overview

The SN74AHCT1G04 device contains one inverter. This device has TTL input levels that allow up translation from 3.3 V to 5 V.

### 7.2 Functional Block Diagram



図 7-1. Logic Diagram (Positive Logic)

### 7.3 Feature Description

- $V_{CC}$  is optimized at 5 V
- Allows up voltage translation from 3.3 V to 5 V
  - Inputs accept  $V_{IH}$  levels of 2 V
- Slow edge rates minimize output ringing
- Inputs are TTL-Voltage compatible

### 7.4 Device Functional Modes

表 7-1. Function Table

INPUT <sup>(1)</sup> A	OUTPUT <sup>(2)</sup> Y
H	L
L	H

(1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care

(2) H = Driving High, L = Driving Low, Z = High Impedance State



## 8 Application and Implementation

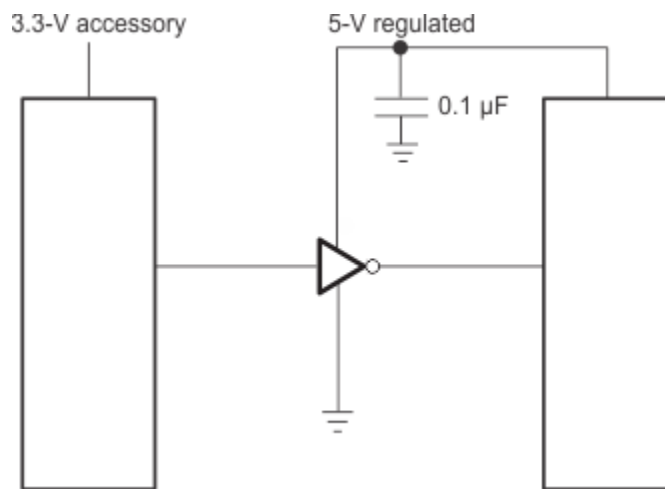
### 注

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### 8.1 Application Information

SN74AHCT1G04 is a low-drive CMOS device that can be used for a multitude of inverting type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The input switching levels have been lowered to accommodate TTL inputs of  $0.8\text{ V }V_{IL}$  and  $2\text{ V }V_{IH}$ . This feature makes it ideal for translating up from 3.3 V to 5 V. [図 8-2](#) shows this type of translation.

### 8.2 Typical Application



**図 8-1. Typical Application Schematic**

#### 8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 8.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - For rise time and fall time specifications, see  $\Delta t/\Delta V$  in the [セクション 5.3](#) table.
  - For specified High and low levels, see  $V_{IH}$  and  $V_{IL}$  in the [セクション 5.3](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend Output Conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

### 8.2.3 Application Curves

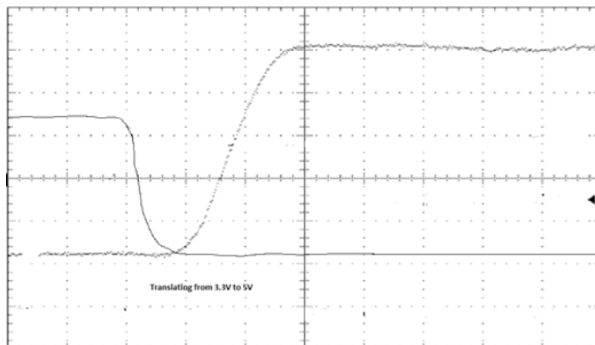


図 8-2. 3.3-V to 5-V Translation

### 8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [セクション 5.3](#) table.

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended. If there are multiple  $V_{CC}$  pins, 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

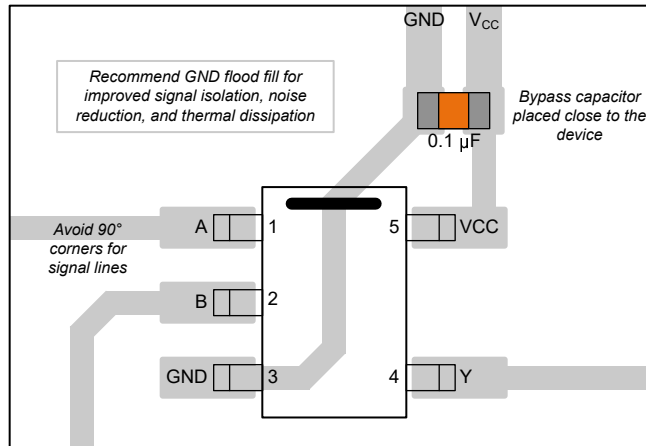
### 8.4 Layout

#### 8.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [図 8-3](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

### 8.4.1.1 Layout Example



☒ 8-3. Layout Diagram

## 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [CMOS Power Consumption and Cpd Calculation application note](#)
- Texas Instruments, [Designing With Logic application note](#)
- Texas Instruments, [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices application note](#)
- Texas Instruments, [Implications of Slow or Floating CMOS Inputs application note](#)

### 9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](#) のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

### 9.3 サポート・リソース

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### 9.5 静電気放電に関する注意事項



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### 9.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

## 10 Revision History

### Changes from Revision Q (October 2023) to Revision R (February 2024) Page

- |  |   |
|--|---|
| • Updated thermal values for DBV package from RθJA = 208.2 to 278, RθJC(top) = 76.1 to 180.5, RθJB = 52.5 to 184.4, ΨJT = 4 to 115.4, ΨJB = 51.8 to 183.4, RθJC(bot) = N/A, all values in °C/W ..... | 5 |
|--|---|

### Changes from Revision P (December 2014) to Revision Q (October 2023) Page

- |  |   |
|--|---|
| • ドキュメント全体にわたって表、図、相互参照の採番方法を更新.....   | 1 |
| • Updated thermal values for DCK package from RθJA = 287.6 to 289.2, RθJC(top) = 97.7 to 205.8, RθJB = 65 to 176.2, ΨJT = 2 to 117.6, ΨJB = 64.2 to 175.1, RθJC(bot) = N/A, all values in °C/W ..... | 5 |

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74AHCT1G04DBVRE4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B04G	<a href="#">Samples</a>
74AHCT1G04DBVRG4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B04G	<a href="#">Samples</a>
74AHCT1G04DBVTG4	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B04G	<a href="#">Samples</a>
74AHCT1G04DCKRE4	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BC3	<a href="#">Samples</a>
74AHCT1G04DCKRG4	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BC3	<a href="#">Samples</a>
74AHCT1G04DCKTG4	OBSOLETE	SC70	DCK	5		TBD	Call TI	Call TI	-40 to 125	BC3	
SN74AHCT1G04DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(38VH, 3C7F, B043, B04G, B04J, B04L, B04S)	<a href="#">Samples</a>
SN74AHCT1G04DBVT	OBSOLETE	SOT-23	DBV	5		TBD	Call TI	Call TI	-40 to 125	(B043, B04G, B04J, B04S)	
SN74AHCT1G04DCKR	ACTIVE	SC70	DCK	5	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	(1QS, BC3, BCG, BCJ, BCL, BCS)	<a href="#">Samples</a>
SN74AHCT1G04DCKT	OBSOLETE	SC70	DCK	5		TBD	Call TI	Call TI	-40 to 125	(BC3, BCG, BCJ, BCS)	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74AHCT1G04 :**

- Automotive : [SN74AHCT1G04-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AHCT1G04DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74AHCT1G04DBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74AHCT1G04DCKRG4	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AHCT1G04DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74AHCT1G04DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AHCT1G04DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
74AHCT1G04DBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
74AHCT1G04DCKRG4	SC70	DCK	5	3000	180.0	180.0	18.0
SN74AHCT1G04DBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0
SN74AHCT1G04DCKR	SC70	DCK	5	3000	210.0	185.0	35.0

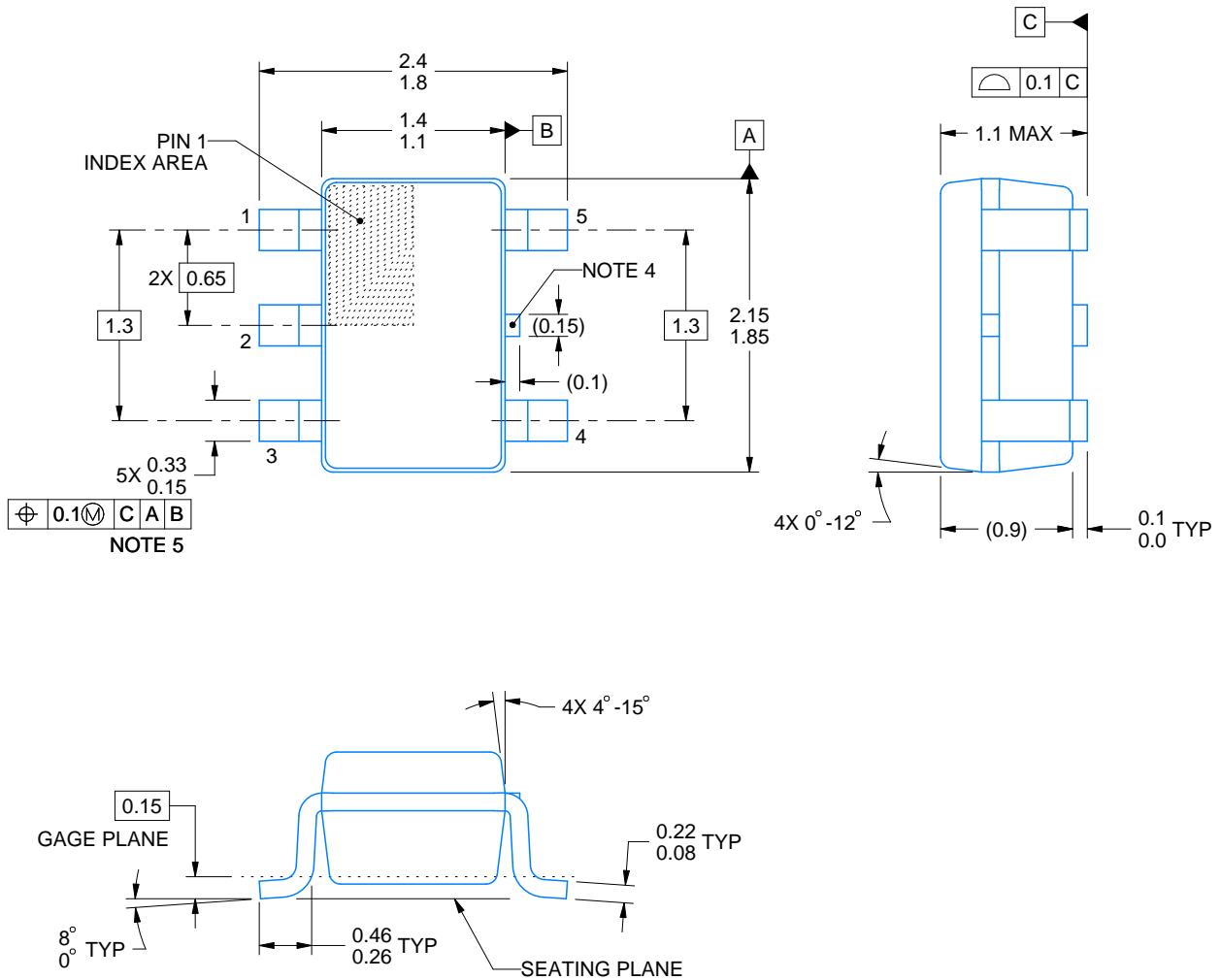
# DCK0005A



## PACKAGE OUTLINE

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



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### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

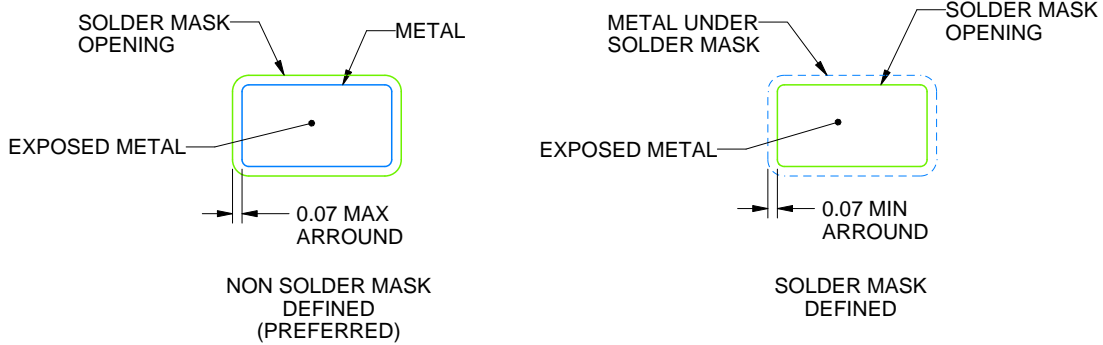
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

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NOTES: (continued)

- 7. Publication IPC-7351 may have alternate designs.
- 8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE: 18X

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NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.



# EXAMPLE BOARD LAYOUT

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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